

Purolite™
Purofine™
PFA600

聚苯乙烯 凝胶, I型 强碱阴树脂, 氯型,
均颗粒

主要应用

- 脱盐 - 工业

产品优势

- 高工作交换容量
- 良好的抗有机物污染能力
- 均颗粒
- 高效再生

包装样式

- 1 CF 编织袋
- 25L 阀口袋
- 5 CF 纤维板桶
- 1M3 立方袋
- 42 ft³ 立方袋

典型物理和化学参数

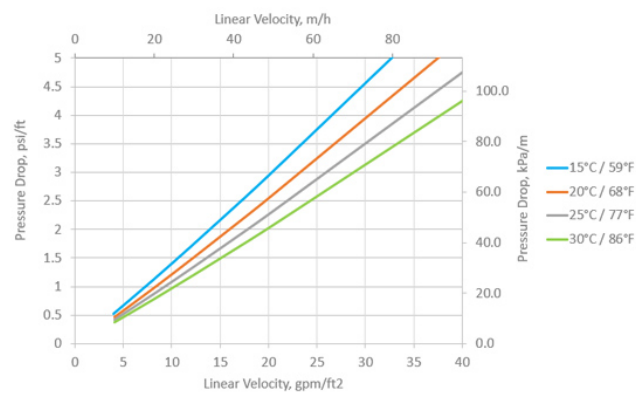
聚合物骨架	凝胶型聚苯乙烯二乙烯苯交联
外观	球状颗粒
官能团	季铵I型
离子型态	Cl ⁻ 型
全交换容量 (最小)	1.4 eq/L (30.6 Kgr/ft³) (Cl ⁻ 型)
含水量	43 - 50 % (Cl ⁻ 型)
平均直径	570 ± 50 µm
均一系数	1.1 - 1.2
转型膨胀率, Cl ⁻ → OH ⁻ (最大)	25 %
比重	1.09
包装密度 (大约)	675 - 700 g/L (42.2 - 43.8 lb/ft³)
温度限制	100 °C (212.0 °F) (Cl ⁻ 型)
温度限制	60 °C (140.0 °F) (OH ⁻ 型)

水力学特性

压降

离子交换树脂的压降取决于粒度分布、床层高度、树脂颗粒间空隙体积，以及物料的流速和粘度。任何对这些参数的影响-比如被树脂床层截住的颗粒物、对树脂床层的异常压缩、床层的不规则分布-都会对压降产生不利影响，造成压头损失。针对不同的物料质量、应用环境和系统设计，流速可能处于10 – 40 BV/h范围内变化。

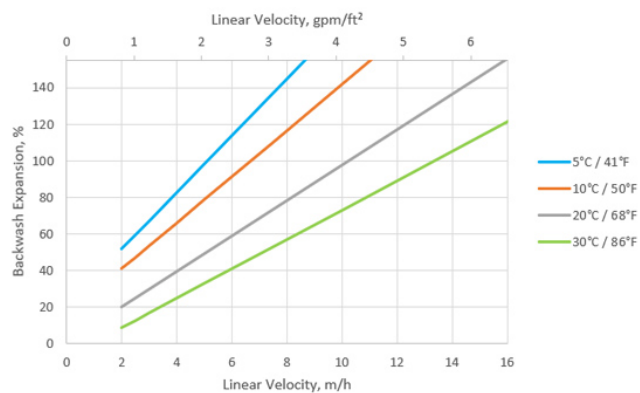
床层压降



反洗

在自下而上反洗过程中，应控制反洗膨胀率在50%到70%之间，至少保持10到15分钟。该操作除去（运行过程中截留的物料中的）颗粒物，清除气泡，并重新规整树脂颗粒，确保最小的流动阻力。第一次投入前，大约30分钟的充分反洗，通常就足以对树脂床层进行适当的规整。值得注意的是，相同流速下反洗膨胀率随温度降低而升高。必须注意，应避免将树脂床层反洗膨胀过甚而导致树脂从顶部流失。

树脂床反洗膨胀率



Ecolab is a global developer, manufacturer, and supplier of Purolite™ Resins including ion exchange, catalyst adsorbent and advanced polymers that make the world cleaner and healthier.

www.puoliteresins.com



We're ready to solve your process challenges.

For further information on products and services, visit www.puoliteresins.com or complete a Contact Us form via PuoliteResins.com/contact-us or use the QR code.

Contact Us Form:



The statements, technical information and recommendations contained herein are believed to be accurate as of the date hereof. Since the conditions and methods of use of the product and of the information referred to herein are beyond our control, Purolite expressly disclaims any and all liability as to any results obtained or arising from any use of the product or reliance on such information; NO WARRANTY OF FITNESS FOR ANY PARTICULAR PURPOSE, WARRANTY OF MERCHANTABILITY OR ANY OTHER WARRANTY, EXPRESSED OR IMPLIED, IS MADE CONCERNING THE GOODS DESCRIBED OR THE INFORMATION PROVIDED HEREIN. The information provided herein relates only to the specific product designated and may not be applicable when such product is used in combination with other materials or in any process. Nothing contained herein constitutes a license to practice under any patent and it should not be construed as an inducement to infringe any patent and the user is advised to take appropriate steps to be sure that any proposed use of the product will not result in patent infringement.